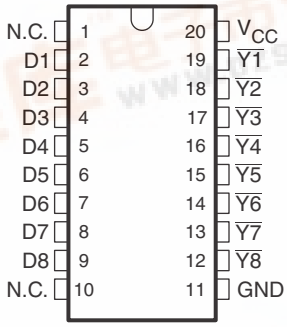
8-BIT DMOS SINK DRIVER

FEATURES

- DMOS Process
- High Voltage Output (V_{ds} = 30 V)
- Output Current on Each Channel (I_{ds} Max = 200 mA)
- Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17
- ESD Protection Exceeds JESD 22
  - 2000-V Human Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged Device Model (C101)
- LED Driver Application
- Output Clamp Diode (Parasitic)

N OR PW PACKAGE
(TOP VIEW)



N.C. – Not internally connected

APPLICATIONS

- Lamp and Display (LED)
- Hammer
- Relay

DESCRIPTION

The TLC59211 is an 8-bit LED and solenoid driver designed for 5-V V_{CC} operation.

The TLC59211 is characterized for operation from –40°C to 85°C.

ORDERING INFORMATION(1)

T_A	PACKAGE(2)		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Reel of 1000	TLC59211IN	Y59211
	TSSOP – PW	Reel of 2000	TLC59211IPWR	Y59211

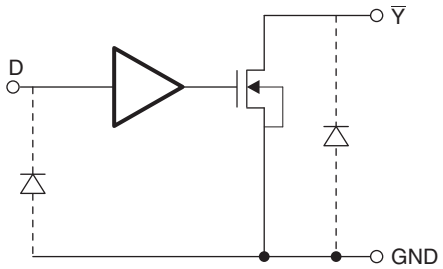
(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

FUNCTION TABLE (EACH LATCH)(1)

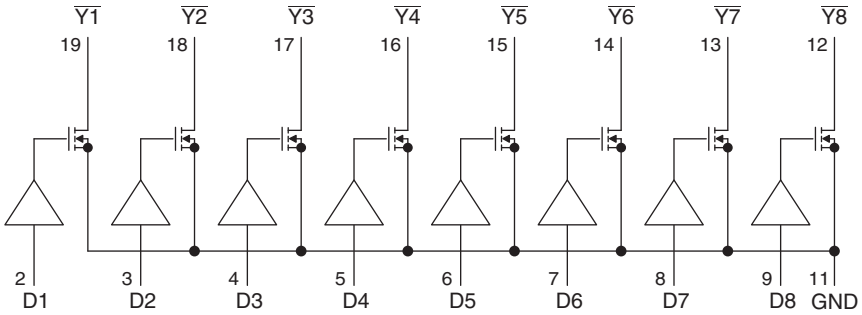
INPUTS	OUTPUT
D	$\overline{Y}$
L	H*
H	L

(1) L: Low-level
H: High-level
H*: with pullup resistor

OUTPUT SCHEMATIC



LOGIC SYMBOL(1)



(1) This symbol is in accordance with ANSI/IEEE Standard 91-1984 and IEC Publication 617-12.

ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		–0.5	7	V
D	Input voltage range		–0.5	7	V
V_{ds}	Output voltage range	H output	–0.5	32	V
I_{ds}	Output current range	1 bit for output low		200	mA
I_{IK}	Input clamp current	V_I < 0 V		–20	mA
θ_{JA}	Package thermal impedance(2)	N package		69	°C/W
		PW package		83	
	Operating free-air temperature range		–40	85	°C
T_{stg}	Storage temperature range		–65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS

V_{CC} = 3 V to 5.5 V

		CONDITIONS		MIN	MAX	UNIT
V_{CC}	Supply voltage			3	5.5	V
V_{IH}	High-level input voltage			V_{CC} × 0.7	V_{CC}	V
V_{IL}	Low-level input voltage			0	V_{CC} × 0.3	V
V_{ds}	Output voltage				30	V
I_{ds}	Output current	N package	Duty cycle < 42%		200	mA
			Duty cycle < 100%		130	
		PW package	Duty cycle < 24%		200	
			Duty cycle < 100%		95	
T_A	Operating free-air temperature			–40	85	°C

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range, V_{CC} = 4.5 V to 5.5 V, T_A = –40°°C to 85°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_{t+}	Positive-going input threshold	D, $\overline{CLR}$, CLK				3.5	V
$V_{t–}$	Negative-going input threshold	D, $\overline{CLR}$, CLK		1.5			V
V_t	Hysteresis	D, $\overline{CLR}$, CLK		0.5		2	V
I_{IH}	High-level input current	V_{CC} = 5.5 V, V_I = 5.5 V			0	1	µA
I_{IL}	Low-level input current	V_{CC} = 5.5 V, V_I = 0 V			0	–1	µA
I_{OZ}	Leakage current	V_{ds}= 30 V				5	µA
I_{off}	Leakage current	V_I = 0 to 5 V, V_O = 0 to 30 V, V_{CC} = 0			0	5	µA
I_{CC}	Supply current	V_I = 0 to 5 V, V_O = 0 to 30 V, V_{CC} = 0	Output = all OFF		0	5	µA
			Output = all ON		0	5	
V_{OL}	Low-level output voltage	V_{CC} = 4.5 V, I_O = 100 mA			0.2	0.35	V
		V_{CC} = 4.5 V, I_O = 200 mA			0.5	0.7	V
r_{ON}	ON-state resistance	V_{CC} = 4.5 V, I_O = 100 mA			2	3.5	Ω
C_i	Input capacitance	V_I = V_{CC} or GND			5		pF

SWITCHING CHARACTERISTICS

over operating free-air temperature range, V_{CC} = 4.5 V to 5.5 V, T_A = –40°°C to 85°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS	LOAD CAPACITANCE	T_A = 25°C			T_A = –40°C to 85°C		UNIT
			MIN	TYP	MAX	MIN	MAX	
t_{TLH}	Output = low to high	C_L = 30 pF, R_L = 240 Ω, 24-V pullup		180	220		260	ns
t_{THL}	Output = high to low	C_L = 30 pF, R_L = 240 Ω, 24-V pullup		290	430		460	ns
t_{PLH}	Output = low to high	C_L = 30 pF, R_L = 240 Ω, 24-V pullup		320	470		510	ns
t_{PHL}	Output = high to low	C_L = 30 pF, R_L = 240 Ω, 24-V pullup		320	470		510	ns

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range, V_{CC} = 3 V to 3.6 V, T_A = –40°°C to 85°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_{t+}	Positive-going input threshold	D				2.52	V
V_{t-}	Negative-going input threshold	D		0.9			V
V_t	Hysteresis	D		0.33		1.32	V
I_{IH}	High-level input current	V_{CC} = 3.6 V, V_I = 3.6V			0	1	µA
I_{IL}	Low-level input current	V_{CC} = 3.6 V, V_I = 0 V			0	–1	µA
I_{OZ}	Leakage current	V_{ds}= 30 V				5	µA
I_{off}	Leakage current	V_I = 0 to 3.6 V, V_O = 0 to 30 V, V_{CC} = 0			0	5	µA
I_{CC}	Supply current	V_I = 0 to 3.6 V, V_{CC} = 3.6 V	Output = all OFF		0	5	µA
			Output = all ON		0	5	
V_{OL}	Low-level output voltage	V_{CC} = 3 V, I_{OL} = 100 mA			0.35	0.7	V
							V
r_{ON}	ON-state resistance	V_{CC} = 3 V, I_O = 100 mA			3.5	7	Ω
C_i	Input capacitance	V_I = V_{CC} or GND			5		pF

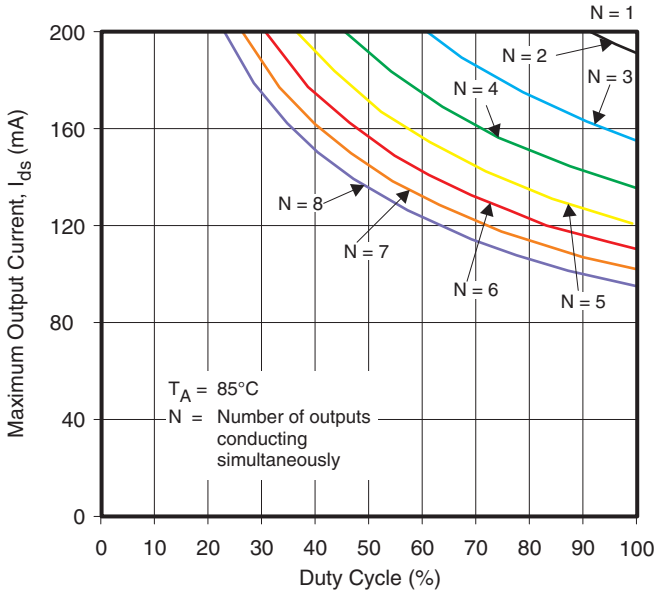
SWITCHING CHARACTERISTICS

over operating free-air temperature range, V_{CC} = 3 V to 3.6 V, T_A = –40°°C to 85°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS	LOAD CAPACITANCE	T_A = 25°C			T_A = –40°C to 85°C		UNIT
			MIN	TYP	MAX	MIN	MAX	
t_{TLH}	Output = low to high	C_L = 30 pF, R_L = 240 Ω, 24-V pullup		200	450		450	ns
t_{THL}	Output = high to low	C_L = 30 pF, R_L = 240 Ω, 24-V pullup		300	450		480	ns
t_{PLH}	Output = low to high	C_L = 30 pF, R_L = 240 Ω, 24-V pullup		450	650		800	ns
t_{PHL}	Output = high to low	C_L = 30 pF, R_L = 240 Ω, 24-V pullup		450	650		800	ns

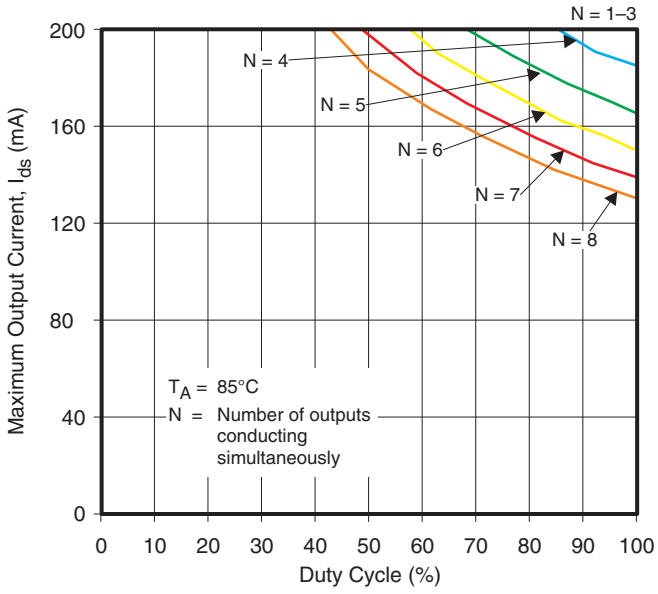
THERMAL INFORMATION

MAXIMUM OUTPUT CURRENT vs DUTY CYCLE



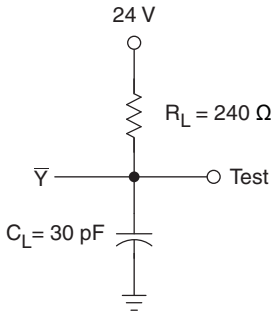
TSSOP (PW) PACKAGE

MAXIMUM OUTPUT CURRENT vs DUTY CYCLE

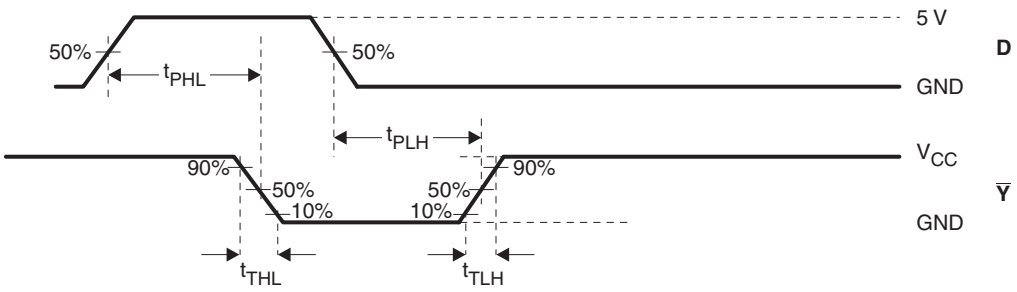


DIP (N) PACKAGE

PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT FOR O/D OUTPUT



VOLTAGE WAVEFORMS

A. C_L includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

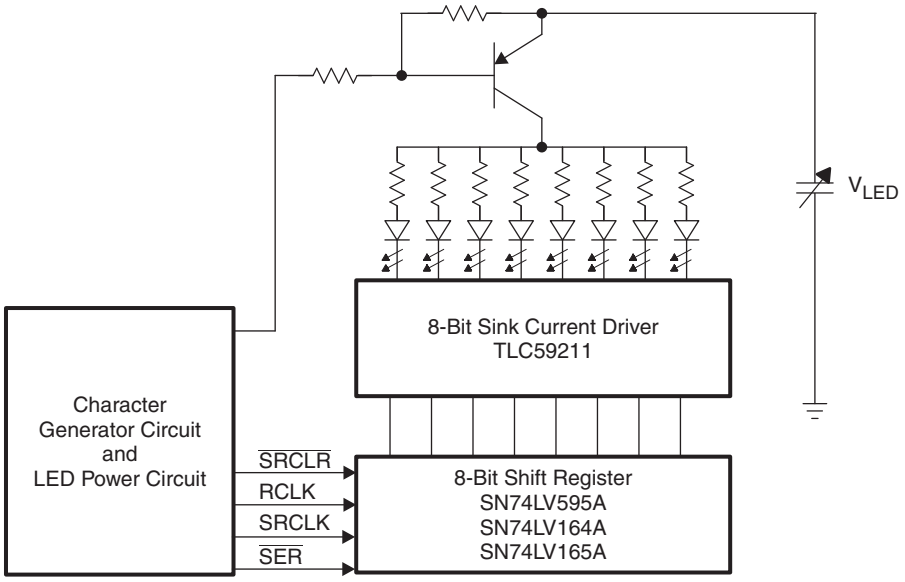
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 3 ns, and t_f ≤ 3 ns.

D. The outputs are measured one at a time with one transition per measurement.

E. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 1. Test Circuit and Voltage Waveforms

APPLICATION INFORMATION



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
TLC59211IN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC59211IPWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

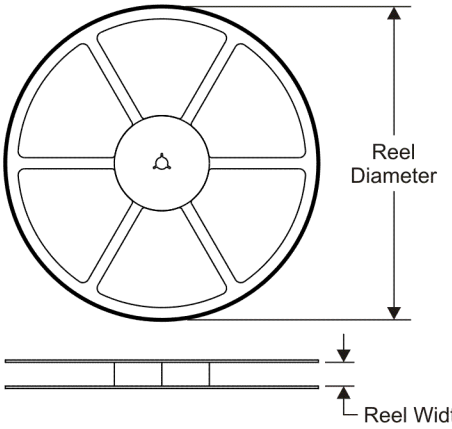
(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

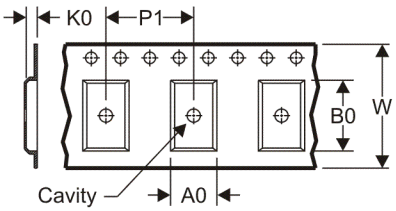
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

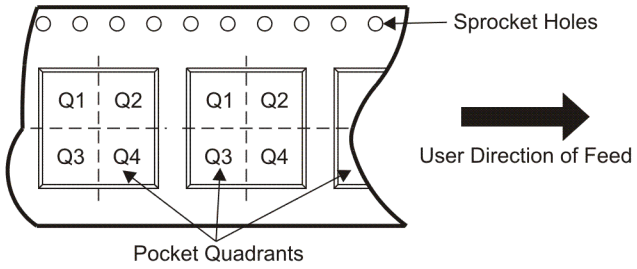


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



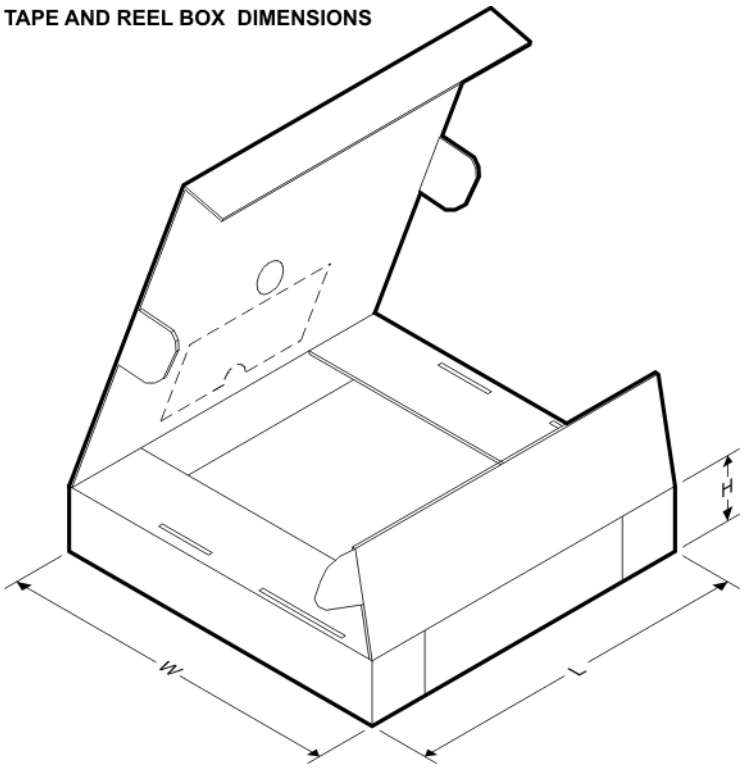
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC59211IPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

3-Apr-2009

TAPE AND REEL BOX DIMENSIONS

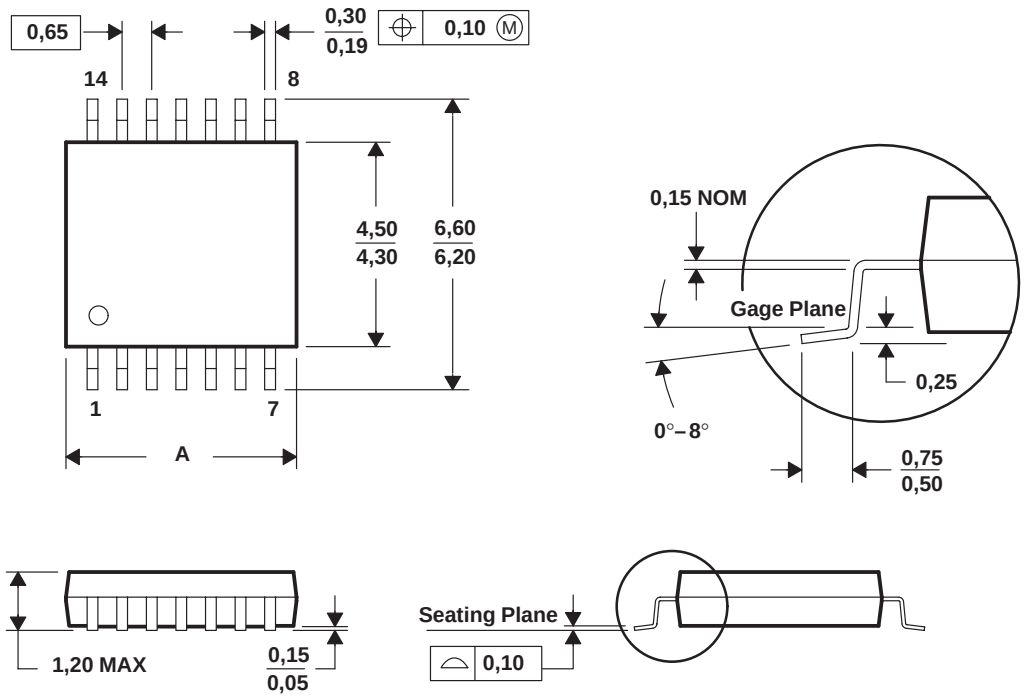


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC59211IPWR	TSSOP	PW	20	2000	346.0	346.0	33.0

PW (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14 PINS SHOWN



DIM \ PINS **	8	14	16	20	24	28
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60

4040064/F 01/97

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

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